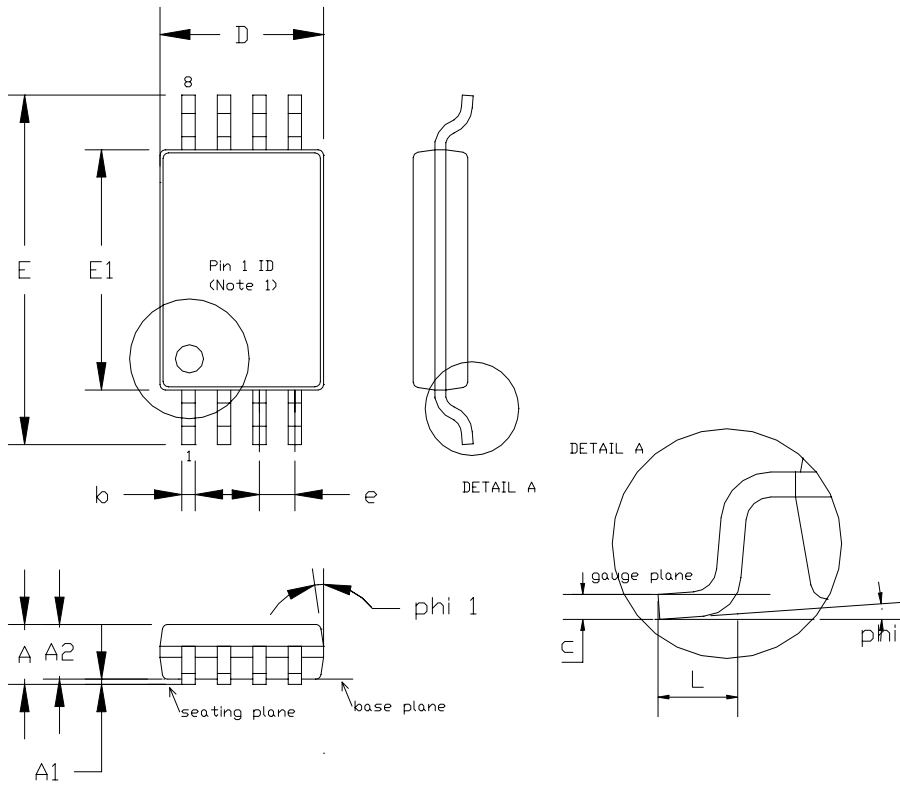


Date: 05.02.2013	PACKAGE OUTLINE SPECIFICATION	elmos[®] Services BV
Author: ASto	8 Lead Thin Shrink Small Outline Package (TSSOP8)	QM-No.: 08SP0668.06

Package Outline and Dimensions are according JEDEC MO-153 F, variant AA.



Description	Symbol	mm			inch		
		min	typ	max	min	typ	max
Package height	A	--	--	1.20	--	--	0.047
Stand off	A1	0.05	--	0.15	0.002	--	0.006
Package body thickness	A2	0.80	1.00	1.05	0.031	0.039	0.041
Width of terminal leads, inclusive lead finish	b	0.19	--	0.30	0.007	--	0.012
Thickness of terminal leads, inclusive lead finish	c	0.09	--	0.20	0.004	--	0.008
Package length	D	2.90	3.00	3.10	0.114	0.118	0.122
Package width	E	6.40 BSC			0.252 BSC		
Package body width	E1	4.30	4.40	4.50	0.169	0.173	0.177
Lead pitch	e	0.65 BSC			0.026 BSC		
Length of terminal for soldering to substrate	L	0.45	0.60	0.75	0.018	0.024	0.030
Angle of lead mounting area	phi [°]	0	--	8	0	--	8
mold release angle	phi1 [°]	12 REF			12 REF		
Number of terminal positions	N	8			8		

Note: the mm values are valid, the inch values contains rounding errors

Note 1: for assembler specific pin1 identification please see QM-document 08SP0363.xx (Pin 1 Specification)